



THE CAPITAL PLACE FOR INNOVATION

PRESS RELEASE

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EMBALLAGE 2014, A "100% USEFUL INNOVATION" PROGRAMME!

A unique platform, a source of inspiration and innovation

EMBALLAGE 2014 is not only a platform for business and sourcing but also for inspiration, thanks to its rich content for each industrial sector. All the industry intelligence is highlighted for the four days of the exhibition by means of conferences, a TV studio broadcasting live, a showcase of packaging innovations and exhibitions to explore the packaging of the future.



Pack Innovation: a showcase of trends in packaging innovation

For many years an EMBALLAGE highlight, enjoyed by visitors and exhibitors alike, the Pack Innovation area is dedicated to exhibitors' latest innovations and trends. The principle? Exhibitors are invited to present their new products to the organisers on an online platform. Once all the applications have been received, the pre-selection committee makes its initial choices. These are submitted for voting by an international jury of journalists, specialised in packaging, to determine the official selection.

The new products selected take pride of place in the innovation showcase for the duration of the show.

The Pack Experts Committee then defines the Pack Experts Innovation Awards among the products, machinery and services selected.



Pack Vision: a conference cycle to get up to speed with the upcoming challenges

To take stock of future regulatory changes, decipher business trends, understand the challenges faced by other countries, the Pack Vision conference programme focuses on sectoral and cross-cutting issues. Speakers are top-level experts, and conferences facilitate the sharing of experience.



You





Themes discussed at EMBALLAGE 2014:

- Regulation and standards
- Results of the 2014 Packaging Observatory
- Fight against waste: clever and active packaging, single dose/unit-dose
- Packaging design (focus on "Wines & Spirits")
- Packaging printing
- Serialisation in healthcare
- The circular economy
- Shopping Live from Tokyo
- Innovative drivers for inter-generational packaging
 Simultaneous interpreting (French/English) is provided at these conferences.
 Take a look at the full programme on www.all4pack.com.



EMBALLAGE & MANUTENTION TV studio: news broadcast live!

Since 2010, a TV studio broadcasting live and dedicated to industry news provides a unique discussion platform to welcome personalities, the media, experts, institutional actors and exhibitors. All the packaging, handling and intralogistics trends will be interpreted from 17 to 20 November 2014.

A few of the major themes* treated during the 2014 exhibition:

- News broadcast on innovation, every morning when the show opens
- Focus on materials wood, plastic, glass, paperboard and metal every day of the show
- Focus on countries: Africa and Italy
- Expert speakers:
- o Brands upset the status quo and consumer habits with new formats
- o The packaging of tomorrow 3.0 e.g. digital and 3D printing
- o E-commerce, m-commerce, drive-in, multi-channel strategy: the repercussions on packaging and handling
- CNE second international meetings France/Europe/Brazil/Canada: "The Circular Economy, Eco-design and Packaging" on Wednesday, 19 November 2014.

Simultaneous interpreting (French/English) is provided, and programmes retransmitted live on the show's Web TV Full programme soon available on www.all4pack.com

*subject to change



SYMOP Forum: the experts take the floor!

At its third show, SYMOP strengthens its commitment to the sector's stakeholders once again. The SYMOP Forum is a lively place for visitors and exhibitors alike, located at the heart of the business arena, for rapid meetings that get

Further information www.all4pack.com









to the point. Top-level speakers, presentations of real-life and transposable customer cases and informal discussions between professionals help to build a clear vision of the market and the solutions available.

The 2014 programme will include:

- Packaging machinery, robotics, industrial vision: technological developments to become more productive, and support during the equipment process
- Export: where to go, when and with which technologies?



Best Pack exhibition – Design by students for virtuous solutions

For the third consecutive exhibition, EMBALLAGE has joined forces with STRATE, a French design school, to explore the packaging of tomorrow through a new design experience.

Best Pack – Design by students for virtuous solutions will welcome students from five international design schools, including Strate (from France, Germany, Italy, Spain and Turkey) in a 200 sqm area in Hall 6.

Their challenge in 2014? To select, from each of the six EMBALLAGE sectors (Beverages & Liquids, Food, Luxury products, Beauty, Health and Multi-industry), packaging that truly reflects their national markets and to propose a better alternative with a packaging design approach.

Their projects will be exhibited throughout the show.

New. This year, the students will have an additional challenge to face during the exhibition: to work in a workshop and deal with current packaging issues. Daily challenges!

The results of their work will be presented in the TV studio on the last day of the exhibition.

Best Pack aims to demonstrate the strengths of design as an approach to and driver of packaging innovation.



Exhibition of The Dieline Awards 2014: the global reference in packaging design!

In just a few years, The Dieline has become one of the reference websites for packaging design. The founder, Andrew GIBBS, shares with us his vision of creative packaging. Find new trends, zany inspirations and brilliant ideas on www.thedieline.com.

This year, EMBALLAGE will welcome an exhibition of award-winning work from The Dieline Awards 2014, its fifth international competition. This rewards the product with the best packaging design. Projects are submitted to a world-renowned jury and selected according to three criteria: Creativity, Marketing and Innovation.

A Sustainable Packaging award was given to the most innovative project in the sustainable development field. An Editor's Choice Award was chosen by the founder of The Dieline Awards.

Further information www.all4pack.com









The Dieline Summit: a new and unique meeting place in Paris, dedicated to packaging design!

The international exhibition EMBALLAGE and THE DIELINE are about to launch an unprecedented event for the new wave of designers and other packaging enthusiasts. This will be held exclusively, and for the very first time in Paris, at the Palais des Congrès, on 16 and 17 November 2014.

These meetings will revolve around rethinking the future of packaging design in terms of innovation in the presence of industry leaders. The aim is to discuss the issues faced by designers and consumers in a global sense. The Summit will start with a networking evening on Sunday, 16 November. A series of conferences and workshops, held on Monday, 17 November, will enable packaging design professionals from the EMEA region to better understand the place of design in their brand strategy and the essential role of packaging design both today and tomorrow.

For further information, the programme and registration for the Summit, see www.all4pack.fr or www.thedielinesummit.com

Join us:







17–20 November 2014, Paris Nord Villepinte France, Halls 4, 5A and 6

- **1,500 exhibitors** in the Packaging, Processing, Printing and Handling sectors
- 100,000 professionals from all over the world expected
- 100 countries represented

For further details, take a look at your **virtual pressroom** http://press.all4pack.com/

The COMEXPOSIUM Group is one of the world's leading event organisers, with 114 public and trade exhibitions covering 17 sectors of activity. Every year, 38,000 exhibitors, of whom 1/3 are international, and 3.5 million visitors, of whom 400,000 are international, are welcomed by the Group. With more than 350 employees, COMEXPOSIUM organises five of the largest French events: SIAL, Intermat, EMBALLAGE, SIMA and Foire de Paris.

Further information www.all4pack.com

